SMTA Press Release

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Wafer-Level Packaging Symposium (WLPS) Program Announced and Registration Now Open

Minneapolis, MN – The SMTA has announced the accepted speakers for the Wafer-Level Packaging Symposium (WLPS). The symposium will be held February 14-16, 2023 at the Marriott Fremont Silicon Valley in Fremont, California.

Packaging technology expert John Lau, Ph. D., will kick off the program Tuesday afternoon with a Professional Development Course on February 14, 2023. The lecture course is titled, “Advanced Packaging: Fan-out, Chiplet, and Heterogeneous Integration”.

The Technical Program consists of over 20 presentations addressing wafer-level packaging (WLP), 3D packaging, and advanced manufacturing and test technologies. The program will conclude with a “Wafer-Level versus Panel Level” panel discussion moderated by Jan Vardaman. View the full program here.

Registration for WLPS is now available online. Discounted rates are available for conference registration made on or before Wednesday, January 25, 2023. All presentations along with the PDC are included in standard registration this year. Visit https://smta.org/wafer for more information. If there are any questions, please call +1-952-920-7682 or email wafer@smta.org.

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SMTA is an international network of professionals who build skills, share practical experience and develop solutions in Electronics Manufacturing (EM), including microsystems, emerging technologies, and related business operations.

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